

Additional Examples 25 and 26 are set forth below for further illustration.

EXAMPLE 25

10 g of polydimethylsiloxanes (silicone oil) was blended with 15 g of spherical gas atomized powder (less than 44 μm particle size) of Al—Si (12.2% atomic % of Si) alloy and 1.5 g of amorphous submicron boron powder (from Aldrich Chemical Co.). The mixture was blended for 2 hours at room temperature to produce a homogeneous tacky glue like paste. This material was then loaded into a polyethylene syringe for convenient dispensing. The glue was applied onto the surfaces of the SiC CFCC (2.6 mm \times 4.1 mm \times 38 mm) bars to be joined together and were spread evenly with a small laboratory spatula. These bars were then butt joined by pushing the bars together with hand pressure and were fired to 1200° C. at the rate of 10° C./min. and holding for 2 hours at 1200° C.

EXAMPLE 26

10 g of methylsquisiloxane polymer (SR350 from GE Silicones) was dissolved in 5 ml of toluene and blended with 15 g of spherical gas atomized powder (less than 44 μm particle size) of Al—Si (12.2% atomic % of Si) alloy and 1.5 g of amorphous submicron boron powder (from Aldrich Chemical Co.). The mixture was gradually concentrated while stirring to produce a homogeneous tacky glue like paste. This material was then loaded into a polyethylene syringe for convenient dispensing. The glue was applied onto the surfaces of the SiC CFCC (2.6 mm \times 41 mm \times 38 mm) bars to be joined together and were spread evenly with a small laboratory spatula. These bars were then butt joined by pushing the bars together with hand pressure and were fired to 1200° C. at the rate of 10° C./min. and holding for 2 hours at 1200° C.

The invention is not limited to the embodiments set forth above, and the invention is set forth in the following claims.

What is claimed is:

1. A bonded assembly comprising first and second materials selected from the group consisting of a ceramic material and a ceramic composite material bonded at an interface by a composite bond joint comprising metallic phase regions comprising aluminum disposed in a ceramic matrix.

2. The assembly of claim 1 wherein the metallic phase regions comprise aluminum and silicon alloy particles.

3. The assembly of claim 2 wherein the aluminum and silicon alloy particles comprise a aluminum-silicon eutectic composition.

4. The assembly of claim 3 wherein the aluminum-silicon eutectic composition comprises about 12.2 atomic % Si.

5. The assembly of claim 1 wherein the composite bond joint further includes aluminum oxide particles dispersed in the ceramic matrix.

6. The assembly of claim 1 wherein the ceramic material comprises monolithic SiC and the ceramic matrix comprises SiC.

7. The assembly of claim 6 wherein the ceramic composite material comprises SiC fibers in a SiC matrix and the ceramic matrix comprises SiC.

8. A repaired material selected from the group consisting of a ceramic material and ceramic composite material comprising a composite filler material bonded in a crack, hole, or depression of said repaired material, said filler material comprising metallic phase regions comprising aluminum disposed in a ceramic matrix.

9. The assembly of claim 8 wherein the metallic phase regions comprise aluminum and silicon alloy particles.

10. The assembly of claim 9 wherein the aluminum and silicon alloy particles comprise a aluminum-silicon eutectic composition.

11. The assembly of claim 10 wherein the aluminum-silicon eutectic composition comprises about 12.2 atomic % Si.

12. The repaired material of claim 8 wherein the composite filler material further includes aluminum oxide particles dispersed in the ceramic matrix.

13. The repaired material of claim 8 wherein the ceramic material comprises monolithic SiC and the ceramic matrix comprises SiC.

14. The repaired material of claim 8 wherein the ceramic composite material comprises SiC fibers disposed in a SiC matrix and the ceramic matrix comprises SiC.

15. The repaired material of claim 8 which is a tube.

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